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(54) **Title**: WAFER HANDLER COMPRISING A VISION SYSTEM

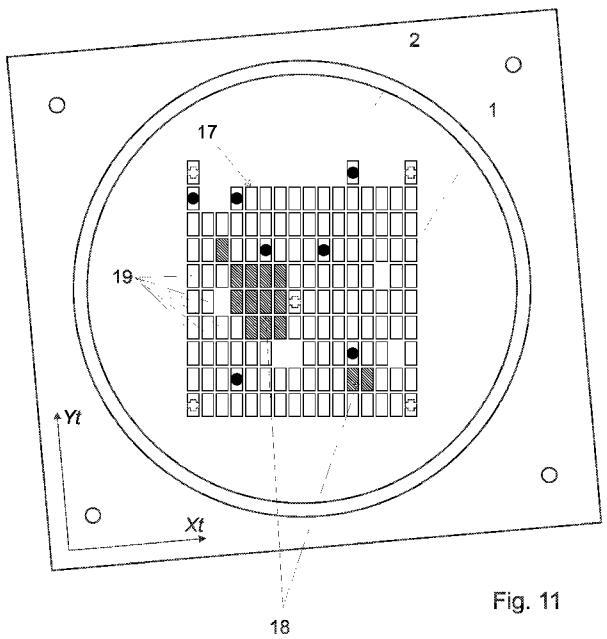


Fig. 11

(57) **Abstract**: According to the present invention there is provided a wafer handler comprising: a wafer loading station (3) for loading a wafer (1) mounted on a tack film (2); a tensioner (30) for tensioning the tacky film; a picking module (66) for successively picking a plurality of devices from said wafer; a vision system (5, 50) with one or several cameras (50) for capturing a first image of said wafer or of portions of said wafer, said first image comprising a plurality of devices, wherein said vision system is arranged for determining from said first image the individual position of a plurality of devices, and wherein the wafer handle further comprises an additional camera (63) positioned proximate to said picking module (66) and arranged for capturing an second image of a device to be picked, wherein the second image is used for fine adjustment of the wafer so that the device to be picked is centered under the picking module.

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